

## Active

- 2 L2: (1) 10/604650
- 2 L3: (0) ((solder near4 mask\$3) (mask\$3 with (epoxy near3 resin 'bt' bismale\$10))) with dielectric
- 2 L4: (0) (solder near4 mask\$3) with dielectric
- 2 L5: (659) (solder near4 mask\$3) with packag\$3
- 2 L6: (0) 5 and ((solder near4 mask\$3) with dielectric)
- 2 L7: (150) 5 and ((solder near4 mask\$3) with (epoxy resin 'bt' bismaleimide adj triazine))
- 2 L9: (19) 7 and ((dielectric) with (epoxy resin 'bt' bismaleimide adj triazine))
- 2 L10: (5) 9 and ((dielectric mask\$) with (thermal\$5 coefficient\$3 expans\$4))
- 2 L11: (11) 9 and (temperature degree)
- 2 L12: (166) (solder near4 mask\$3) with (epoxy near3 resin 'bt' bismale\$10)
- 2 L13: (3421) (dielectric) with (epoxy near3 resin 'bt' bismale\$10)
- 2 L14: (15927) (dielectric insulat\$3) with (epoxy near3 resin 'bt' bismale\$10)
- 2 L15: (662) (solder near4 mask\$3) with dielectric
- 2 L16: (13) ((solder near4 mask\$3) with dielectric) with (epoxy near3 resin 'bt' bismale\$10)
- 2 L17: (3421) 13 and 13
- 2 L18: (240) 17 and (solder with (expans\$4 coefficient thermal\$3))
- 2 L19: (19) 12 and 13
- 2 L20: (119) 18 and (dielectric with (expans\$4 coefficient thermal\$3))
- 2 L21: (101) 20 and packag\$3
- 2 L22: (618) (solder adj mask\$3) with dielectric
- 2 L23: (25) 22 and (solder ) with (epoxy near3 resin 'bt' bismale\$10)
- 2 L26: (18) 23 and (dielectric) with (epoxy near3 resin 'bt' bismale\$10)
- 2 L27: (701) (solder adj mask\$3 soldermask\$3) with dielectric
- 2 L28: (158) 27 and (solder adj mask\$3 soldermask\$3) with (epoxy resin 'bt' bismaleimide adj triazine)
- 2 L29: (131) 28 and (epoxy resin 'bt' bismaleimide adj triazine) with dielectric
- 2 L30: (131) 29 and (epoxy resin 'bt' bismaleimide adj triazine dielectric solder adj mask\$3 solder...
- 2 L31: (131) 30 and (epoxy resin 'bt' bismaleimide adj triazine dielectric solder adj mask\$3 solder...
- 2 L32: (0) 10/604650

20 and (expans\$4 coefficient thermal\$3) with (solder adj mask\$3 soldermask\$3 dielectric)

U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XR	Retrieval C	Inventor	S	C	E	3	4	5	6
1	C	US 20040202	20041202	18	Compact electromagnetic	333/24R	333/109		Benham, John R. et al.	<input checked="" type="checkbox"/>						
2	C	US 20040202	20041007	26	Methods for assembly and	438/108	438/126		Lee, Teck Kheng	<input checked="" type="checkbox"/>						
4																

Title  Details  HTML

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4659

U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XR	Retrieval C	Inventor	S	C	P	3	4
1	<input checked="" type="checkbox"/>	US 20040239438	20041202	18	Compact electromagnetic coupler for use with digital	333/24R	333/109		Benham, John R. et al.	<input checked="" type="checkbox"/>				
2	<input checked="" type="checkbox"/>	US 20040197955	20041007	26	Methods for assembly and packaging of flip chip	438/108	438/126		Lee, Teck Kheng	<input checked="" type="checkbox"/>				
3	<input checked="" type="checkbox"/>	US 20040197952	20041007	25	Methods for assembly and packaging of flip chip	438/107			Lee, Teck Kheng	<input checked="" type="checkbox"/>				
4	<input checked="" type="checkbox"/>	US 20040159957	20040819	32	Interposer substrate and wafer scale interposer	257/778	257/E21.503; 257/E23.004		Lee, Teck Kheng	<input checked="" type="checkbox"/>				
5	<input checked="" type="checkbox"/>	US 20040137659	20040715	16	[METHOD OF FABRICATING A SOLDER	438/106			Ding, Yi-Chuan et al.	<input checked="" type="checkbox"/>				
6	<input checked="" type="checkbox"/>	US 20040104463	20040603	16	Crack resistant interconnect module	257/686	257/E23.062; 257/E23.069;		Gorrell, Robin E. et al.	<input checked="" type="checkbox"/>				
7	<input checked="" type="checkbox"/>	US 20030166312	20030904	27	Methods for assembly and packaging of flip chip	438/107	257/E23.004; 257/E23.067;		Lee, Teck Kheng	<input checked="" type="checkbox"/>				
8	<input checked="" type="checkbox"/>	US 20030164548	20030904	29	Flip chip packaging using recessed interposer terminals	257/738	257/678; 257/737;		Lee, Teck Kheng	<input checked="" type="checkbox"/>				
9	<input checked="" type="checkbox"/>	US 20030164541	20030904	34	Method and apparatus for dielectric filling of flip chip	257/686	257/E21.503; 257/E23.004		Lee, Teck Kheng	<input checked="" type="checkbox"/>				
10	<input checked="" type="checkbox"/>	US 20030003406	20030102	9	Direct imaging process for forming resist pattern on a	430/325	430/302; 430/346;		Grunwald, John J. et al	<input checked="" type="checkbox"/>				
11	<input checked="" type="checkbox"/>	US 200110041389	20011115	14	Semiconductor device having a thermoset-containing	438/118			Farquhar, Donald S. et al.	<input checked="" type="checkbox"/>				
12	<input checked="" type="checkbox"/>	US 20010005548	20010628	14	Semiconductor device having a thermoset-containing	428/325	428/328; 428/422		Farquhar, Donald S. et al.	<input checked="" type="checkbox"/>				
13	<input checked="" type="checkbox"/>	US 6632588 B2	20031014	8	Direct imaging process for forming resist pattern on a	430/302	430/325; 430/944;		Grunwald, John J. et al	<input checked="" type="checkbox"/>				
14	<input checked="" type="checkbox"/>	US 6534160 B2	20030318	13	Semiconductor device having a thermoset-containing	428/209	174/258; 174/259;		Farquhar, Donald S. et al.	<input checked="" type="checkbox"/>				

S1.1.1. (39) 3D model (expansive coefficient thermal 3) with (solder adh. mask 3; solder mask 3; dielectric 3)										
U	Document ID	Issue Date	Pages	Title	Current OR	Current XR	Retrieval C	Inventor	S	C
15	US 6468813	20021022	11	Method of automatically identifying and skipping	438/7	257/676; 257/E23.179;		Chao; Te Tsung et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
16	US 6426545	20020730	18	Integrated circuit structures and methods employing a low	257/633	257/508; 257/701;		Eichelberger, Charles W. et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
17	US 6254972	20010703	13	Semiconductor device having a thermoset-containing	428/209	174/258; 174/259;		Farquhar; Donald S. et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
18	US 6212076	20010403	13	Enhanced heat-dissipating printed circuit board package	361/720	174/252; 361/749		MacQuarrie; Stephen W. et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
19	US 6007349 A	19991228	18	Flexible contact post and post socket and associated	439/71	257/E23.021; 257/E23.068;		Distefano; Thomas H. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
20	US 5906042 A	19990525	31	Method and structure to interconnect traces of two	29/852	257/E23.171; 257/E23.174;		Lan; James J. D. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
21	US 5667934 A	19970916	4	Thermally stable photoimaging composition	430/280.1	430/315; 522/31		Markovich; Voya Rista et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
22	US 5665526 A	19970909	4	Thermally stable photoimaging composition	430/325	430/280.1; 430/315;		Markovich; Voya Rista et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
23	US 5641608 A	19970624	9	Direct imaging process for forming resist pattern on a	430/302	101/465; 101/467;		Grunwald; John J. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
24	US 5304252 A	19940419	7	Method of removing a permanent photoimagable	134/2	134/29; 134/38;		Condra; Richard C. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
25	US 5218234 A	19930608	7	Semiconductor device with controlled spread polymeric	257/787	257/738; 257/774;		Thompson; Kenneth R. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
26	US 5206116 A	19930427	8	Light-sensitive composition for use as a soldermask and	430/311	430/315; 430/324;		Daniels; George R. E. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
27	US 4976813 A	19901211	8	Process for using a composition for a solder	156/230	156/249; 427/259;		Salensky; George A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>
28	US 4954185 A	19900904	7	Method of applying adherent coating on copper	148/282	148/269; 148/272;		Kohm; Thomas S.	<input checked="" type="checkbox"/>	<input type="checkbox"/>

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26	<input checked="" type="checkbox"/>	US 5206116 A	19930427	8	Light-sensitive composition for use as a soldermask and	430/311	430/315; 430/324;		Daniels; George R. E. et al.	<input checked="" type="checkbox"/>					
27	<input checked="" type="checkbox"/>	US 4976813 A	19901211	8	Process for using a composition for a solder	156/230	156/249; 427/259;		Salensky; George A. et al.	<input checked="" type="checkbox"/>					
28	<input checked="" type="checkbox"/>	US 4954185 A	19900904	7	Method of applying adherent coating on copper	148/282	148/269; 148/272;		Kohn; Thomas S.	<input checked="" type="checkbox"/>					
29	<input checked="" type="checkbox"/>	US 4927742 A	19900522	12	Multilayer printed wiring boards	430/311	216/20; 216/52;		Kohn; Thomas S.	<input checked="" type="checkbox"/>					
30	<input checked="" type="checkbox"/>	US 4908096 A	19900313	22	Photodefinaile interlevel dielectrics	216/49	427/488; 427/534;		Zupancic; Joseph J.	<input checked="" type="checkbox"/>					
31	<input checked="" type="checkbox"/>	US 4859807 A	19890822	24	Wire scribed circuit boards and method of manufacture	174/259	29/850		Swiggett; Brian E. et al.	<input checked="" type="checkbox"/>					
32	<input checked="" type="checkbox"/>	US 4804575 A	19890214	12	Multilayer printed wiring boards	428/209	174/259; 428/460;		Kohn; Thomas S.	<input checked="" type="checkbox"/>					
33	<input checked="" type="checkbox"/>	US 4774279 A	19880927	7	Adherent coating for copper	524/509	525/58		Kohn; Thomas S.	<input checked="" type="checkbox"/>					
34	<input checked="" type="checkbox"/>	US 4717643 A	19880105	6	No thermal cure dry film solder mask	430/284.1	430/18; 430/287.1;		Scheve; Bernard J. et al.	<input checked="" type="checkbox"/>					
35	<input checked="" type="checkbox"/>	US 4711026 A	19871208	23	Method of making wires scribed circuit boards	29/850	174/259		Swiggett; Brian E. et al.	<input checked="" type="checkbox"/>					
36	<input checked="" type="checkbox"/>	US 4522888 A	19850611	9	Electrical conductors arranged in multiple layers	428/546	427/103; 427/123;		Eichelberger; Charles W. et al.	<input checked="" type="checkbox"/>					
37	<input checked="" type="checkbox"/>	US 4416914 A	19831122	10	Electrical conductors arranged in multiple layers and	427/510	427/123; 427/205;		Eichelberger; Charles W. et al.	<input checked="" type="checkbox"/>					
38	<input checked="" type="checkbox"/>	JP 11231520 A	19990827	14	POSITIVE PHOTOMAGING				HAWKINS, ROBERT E et al.	<input checked="" type="checkbox"/>					